AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-5 (canceled).

Claim 6 (new): A surface acoustic wave filter comprising:

a mount board including a land;

a device chip in which a wiring pattern including an IDT and a pad electrically connected to the IDT is provided on one of a pair of parallel and opposing principal surfaces of a piezoelectric substrate, the pad being disposed so as to oppose the land of the mount board, the pad and the land being electrically connected through a bump; and

a resin film covering the other principal surface of the piezoelectric substrate and sealing the device chip; wherein

an area of the one of the principal surfaces of the piezoelectric substrate is greater than an area of the other principal surface of the piezoelectric substrate.

Claim 7 (new): The surface acoustic wave filter according to Claim 6, wherein each peripheral surface of the piezoelectric substrate extending between the pair of principal surfaces includes a parallel planar portion which is substantially parallel to the pair of principal surfaces of the piezoelectric substrate and a vertical planar portion which is substantially perpendicular to the pair of principal surfaces of the piezoelectric

substrate, such that each of the peripheral surfaces of the piezoelectric substrate includes a stepped portion including at least one step.

Claim 8 (new): The surface acoustic wave filter according to Claim 6, wherein each peripheral surface of the piezoelectric substrate extending between the pair of principal surfaces includes a tapered portion extending along an outer edge of the other principal surface of the piezoelectric substrate.

Claim 9 (new): The surface acoustic wave filter according to Claim 6, wherein each peripheral surface of the piezoelectric substrate extending between the pair of principal surfaces includes a curved portion extending along an outer edge of the other principal surface of the piezoelectric substrate.

Claim 10 (new): The surface acoustic wave filter according to Claim 6, wherein the piezoelectric substrate is made of one of $LiTaO_3$ and $LiNbO_3$.

Claim 11 (new): The surface acoustic wave filter according to Claim 6, wherein the land is made of Au.

Claim 12 (new): The surface acoustic wave filter according to Claim 6, wherein the bump is made of one of Au and solder.

Claim 13 (new): The surface acoustic wave filter according to Claim 7, wherein a thickness of the at least one step is substantially 50% $\pm$ 15% of a thickness of the piezoelectric substrate.

Claim 14 (new): A method of producing surface acoustic wave filters comprising:

a first step of producing a plurality of device chips, each having a wiring pattern formed on one of a pair of opposing principal surfaces of a piezoelectric substrate, each wiring pattern including an IDT and a pad electrically connected to the IDT;

a second step of mounting the plurality of device chips on a board aggregate so as to be spaced apart from each other by arranging the one of the principal surfaces of each device chip so as to oppose the board aggregate and electrically connecting the one of the principal surfaces of each device chip to the board aggregate through a bump;

a third step of sealing the device chips with a resin film by covering the device chips mounted to the board aggregate with the resin film and heating and pressing the resin film; and

a fourth step of severing the surface acoustic wave filters from each other by cutting portions of the resin film and the board aggregate between the device chips that are adjacent to each other; wherein

the first step includes a step of forming the one of the principal surface of each piezoelectric substrate so as to have an area that is greater than an area of the other principal surface of each piezoelectric substrate by removing a portion of each piezoelectric substrate near an outer edge of the other principal surface.

Claim 15 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate includes the step of forming a parallel planar portion which is substantially parallel to the pair of principal surfaces of the piezoelectric substrate and a vertical planar portion

which is substantially perpendicular to the pair of principal surfaces of the piezoelectric substrate, such that each of peripheral surface of each of the piezoelectric substrates includes a stepped portion including at least one step.

Claim 16 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate produces a tapered portion extending along an outer edge of the other principal surface of each piezoelectric substrate.

Claim 17 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate produces a curved portion extending along an outer edge of the other principal surface of each piezoelectric substrate.

Claim 18 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the piezoelectric substrate is made of one of $LiTaO_3$ and $LiNbO_3$.

Claim 19 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the bump is made of one of Au and solder.

Claim 20 (new): The method of producing surface acoustic wave filters according to Claim 15, wherein a thickness of the at least one step is substantially 50% $\pm$ 15% of a thickness of each piezoelectric substrate.

Claim 21 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate near an outer edge of the other principal surface is performed by a step of dicing.

Claim 22 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate near an outer edge of the other principal surface is performed by a step of acid etching.

Claim 23 (new): The method of producing surface acoustic wave filters according to Claim 14, wherein the step of removing a portion of each piezoelectric substrate near an outer edge of the other principal surface is performed by a step of dry etching using Ar gas.

Claim 24 (new): The method of producing surface acoustic wave filters according to Claim 21, wherein the step of dicing is performed using a dicer blade having a cutting edge that corresponds to a desired shape of the removed portion of each piezoelectric substrate.

Claim 25 (new): The method of producing surface acoustic wave filters according to Claim 24, wherein the cutting edge has a substantially V-shaped cross section.